



Material Content Data Sheet



Sales Product Name		BSD840N H6327		Issued		19. July 2018		
MA#		MA000937332						
Package		PG-SOT363-6-1		Weight*		6.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.04		394	
	noble metal	gold	7440-57-5	0.010	0.15		1528	
	inorganic material	silicon	7440-21-3	0.147	2.33	2.52	23314	25236
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		91	
	non noble metal	titanium	7440-32-6	0.003	0.05		458	
	non noble metal	chromium	7440-47-3	0.009	0.14		1373	
	non noble metal	copper	7440-50-8	2.869	45.57	45.77	455678	457600
wire	non noble metal	copper	7440-50-8	0.010	0.16	0.16	1579	1579
encapsulation	organic material	carbon black	1333-86-4	0.030	0.47		4728	
	plastics	epoxy resin	-	0.640	10.16		101650	
	inorganic material	silicondioxide	60676-86-0	2.307	36.64	47.27	366414	472792
leadfinish	non noble metal	tin	7440-31-5	0.213	3.39	3.39	33865	33865
plating	noble metal	silver	7440-22-4	0.056	0.89	0.89	8928	8928
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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